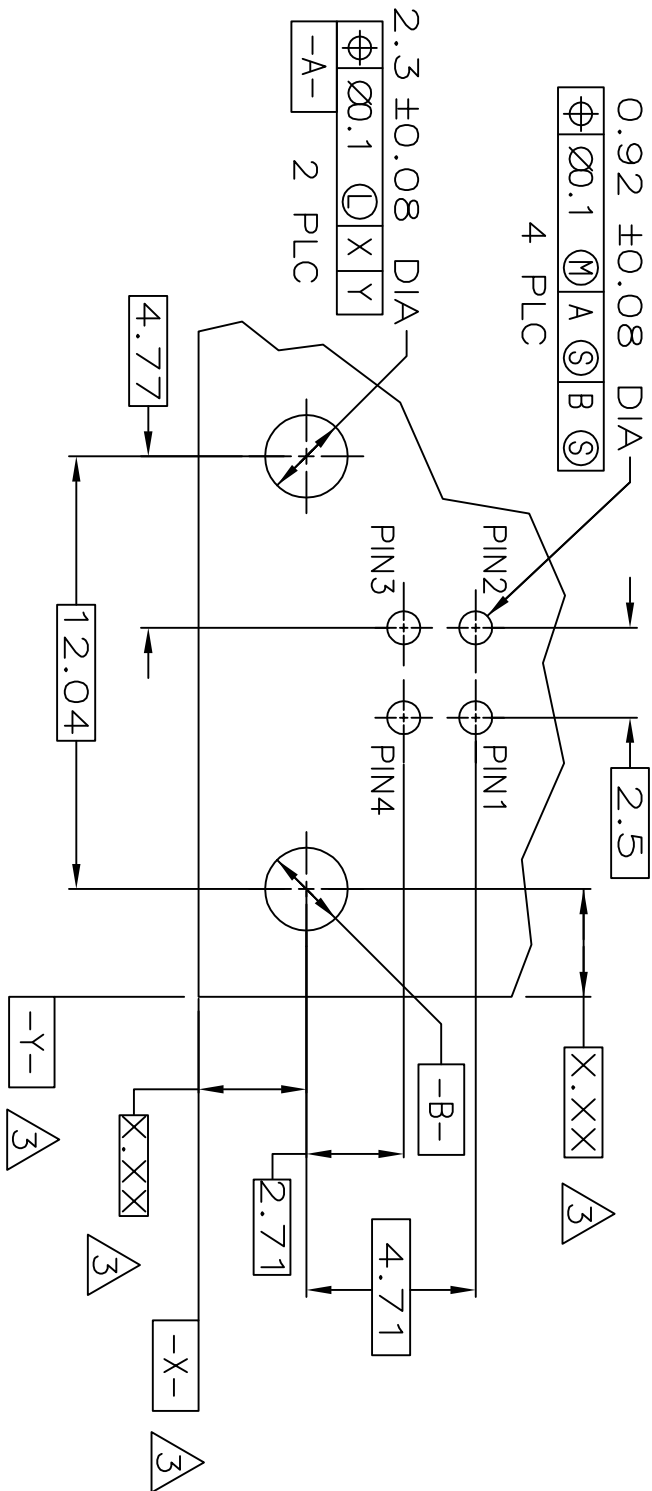
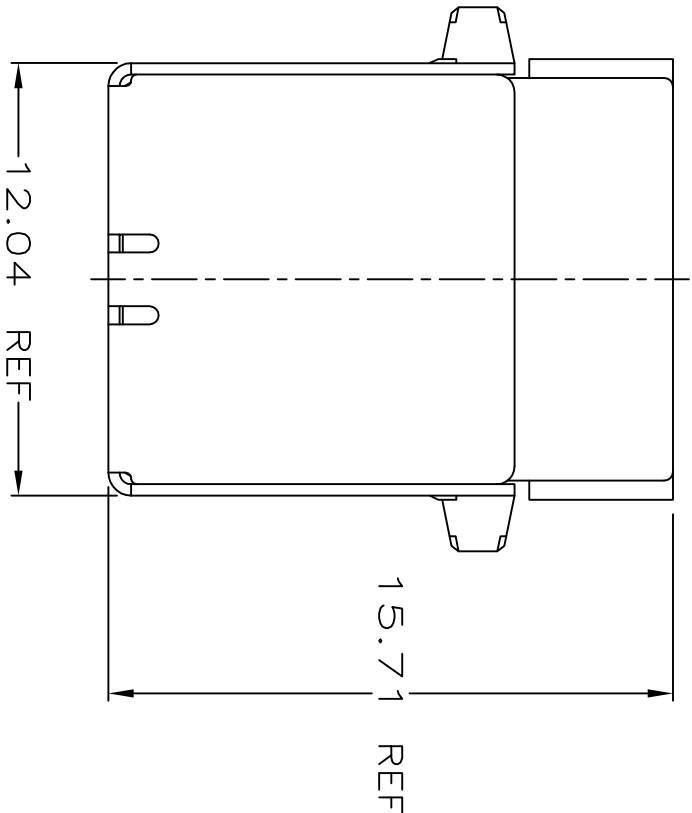
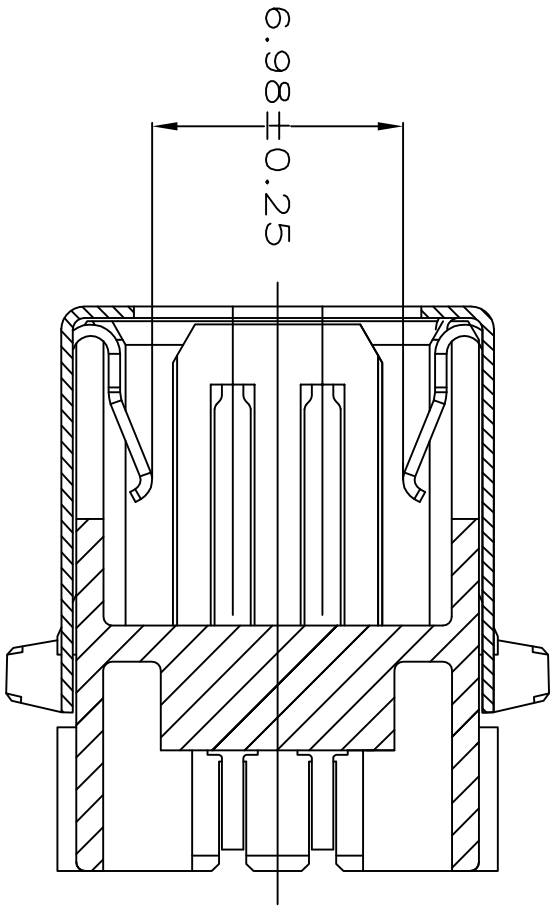
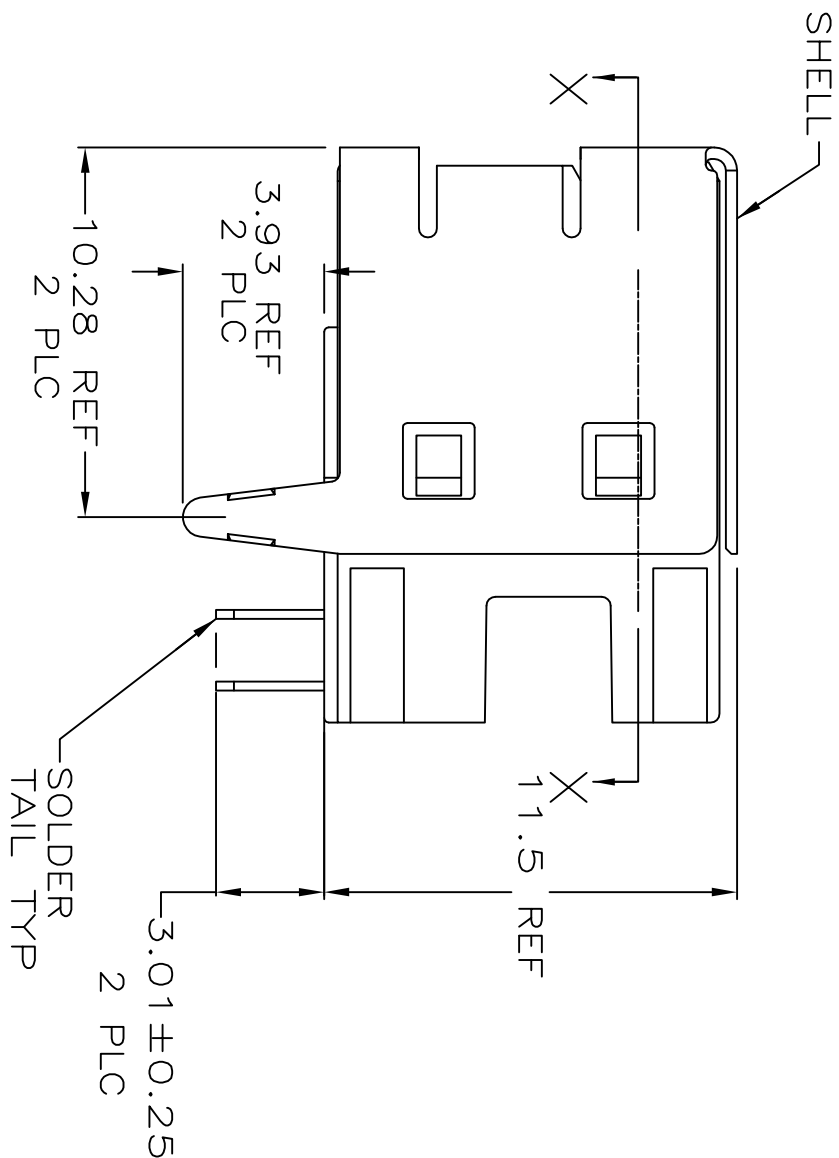
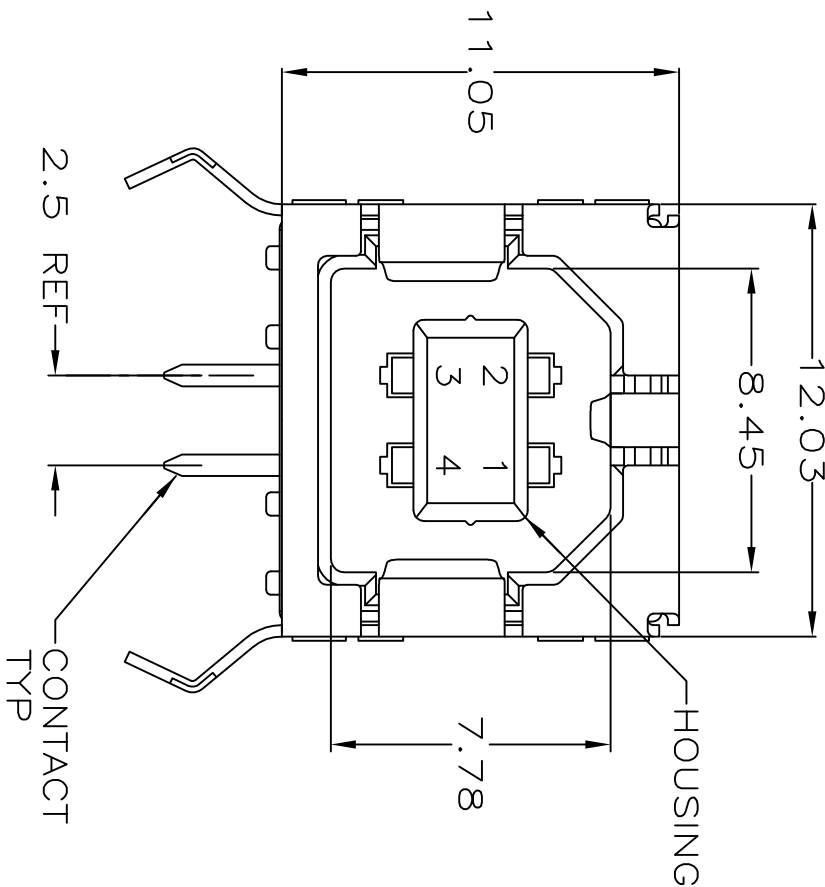




PC BOARD MOUNTING DIMENSIONS



LOC		DIST		REVISIONS			
ES	00	P	LIR	DESCRIPTION	DATE	OWN	APVD
				D2 REVISED ECR-08-018445	23Jul08	A.Z	S.Y

1 MATERIAL:
SHELL & CONTACTS: COPPER ALLOY.
HOUSING: UL 94V-0 RATED, THERMOPLASTIC, BLACK.

2 PLATING:
CONTACTS: 0.076μm MINIMUM GOLD OVER 0.76μm MINIMUM PALLADIUM-NICKEL ON MATING AREA.
3.8μm MINIMUM MATTE TIN ON SOLDER TAILS.
BOTH OVER 1.27μm MINIMUM NICKEL.
CONTACT ALTERNATE PLATING: 0.76μm MIN GOLD ON MATING AREA, 3.8μm MIN MATTE TIN ON SOLDER TAILS, BOTH OVER 1.27μm MIN NICKEL.
SHELL: 2.0~5.0μm MINIMUM TIN.
DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER.

3 DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER.
4 RECOMMENDED PC BOARD THICKNESS OF 1.57.
5 PLATING:
CONTACTS: 0.76μm MINIMUM GOLD ON MATING AREA, 3.8μm MINIMUM MATTE TIN ON SOLDER TAILS, BOTH OVER 1.27μm MINIMUM NICKEL.
SHELL: 2.0~5.0μm MINIMUM TIN.

6 PLATING:
CONTACTS: 0.38μm MINIMUM GOLD ON MATING AREA, 3.8μm MINIMUM MATTE TIN ON SOLDER TAILS, BOTH OVER 1.27μm MINIMUM NICKEL.
SHELL: 2.0~5.0μm MINIMUM TIN.
7 RECOMMEND:
MATING FORCE: 35N MAX.
UNMATING FORCE: 13N MIN.
RECOMMENDED MATING PLUG SHOULD MEET USB2.0 STANDARD.

DIMENSIONS:		TOLERANCES UNLESS OTHERWISE SPECIFIED:		PLATING		HIGH TEMPERATURE COMPATIBLE		HOUSING COLOR		PART NUMBER	
mm		OTHERWISE SPECIFIED:		PLATING		HIGH TEMPERATURE COMPATIBLE		HOUSING COLOR		PART NUMBER	
0 PLC		±-		NO		NO		BLACK		292304-5	
1 PLC		±-		NO		NO		BLACK		292304-4	
2 PLC		±0.1		YES		YES		BLACK		292304-3	
3 PLC		±-		YES		YES		NATURAL		292304-2	
4 PLC		±-		NO		NO		BLACK		292304-1	
FINISH		±-		NO		NO		BLACK		292304-1	
MATERIAL		—		—		—		—		—	
1		2		CUSTOMER DRAWING		A2 00779		C=292304		SCALE 5:1	
2		3		SHEET 1 OF 1		REV D2		292304		292304	